

REMARKS

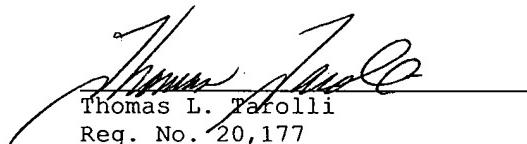
Examination of the above-identified application in view of the present amendment is respectfully requested.

The present amendment before action removes the multiple dependency appearing in the claims.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version With Markings to Show Changes Made".

An early action on the merits is respectfully requested. Please charge any deficiency or credit any overpayment in the fees for this matter to our Deposit Account No. 20-0090.

Respectfully submitted,



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"Version With Markings to Show Changes Made"

In the Claims:

Claims 1-6 remain unchanged.

Claim 7 has been amended, as follows:

7. (Amended) A circuit board according to ~~one of claims~~
~~2-6~~ claim 2, characterized in that the carrier plates (10, 16)
are each made of an electrically insulating material which is
used as the base material for the production of electric
circuitboards, preferably an Aramid-reinforced resin.

Claim 8 has been amended, as follows:

8. (Amended) A circuitboard according to ~~one of claims~~
~~1-7~~ claim 1, characterized in that the thin glass layers (11,
17) have a thickness of less than or equal to 1.1 mm and are
made of a borosilicate glass.

Claim 9 has been amended, as follows:

9. (Amended) A circuitboard according to ~~one of claims~~
~~1-8~~ claim 1, characterized in that the thin glass layers (11,
17) and the carrier plates (10, 16) are glued or pressed
together.

Claim 10 has been amended, as follows:

10. (Amended) A circuitboard according to ~~one of claims~~
~~1-9~~ claim 1, characterized in that at least individual layers
of the thin glass layers (11, 17) are designed as continuous
layers.

Claim 11 has been amended, as follows:

11. (Amended) A circuitboard according to ~~one of claims~~
~~1-9~~ claim 1, characterized in that at least individual layers
of the thin glass layers (11, 17) are structured so as to form
individual optical conductors (13) within the layer, separated
from one another by interspaces (12).

Claim 12 remains unchanged.

Claim 13 has been amended, as follows:

13. (Amended) A circuitboard according to ~~one of claims~~
~~11 and 12~~ claim 11, characterized in that the interspaces (12)
between the optical conductors (13) are filled with a filling
material (14, 18).

Claim 14 has been amended, as follows:

14. (Amended) A circuitboard according to ~~one of claims~~
~~1-13~~ claim 1, characterized in that coupling openings (26, 28)
are provided for optical coupling of optically active elements
(25, 27) arranged on the top and or bottom sides of the
circuitboard (30), so that the concealed thin glass layer(s)
(11, 17) or optical conductors (13) located in an optical
conduction level (OL) are accessible from the outside through
these coupling openings.

Claim 15 has been amended, as follows:

15. (Amended) A method of producing a circuitboard
according to ~~one of claims 1 through 14~~ claim 1, characterized
in that in a first step at least one thin glass layer (11, 17)
is joined over the entire area to at least one carrier plate

(10, 16) to form an optical sandwich (15; 15.1, ..., 15.3), and in a second step, the optical sandwich (15; 15.1, ..., 15.3) is connected to the circuitboard (30) as an optical conduction level (OL) having one or more electrical conduction levels (EL) in a stack arrangement.

Claim 16 remains unchanged.

Claim 17 has been amended, as follows:

17. (Amended) A method according to ~~one of claims 15 and~~ ~~16~~ claim 15, characterized in that the thin glass layer (11, 17) joined to the carrier plate (10, 16) is structured between the first and second steps.

Claim 18 remains unchanged.

Claim 19 remains unchanged.

Claim 20 has been amended, as follows:

20. (Amended) A method according to ~~one of claims 17~~ ~~through 19~~ claim 17, characterized in that the free surface area of the structured thin glass layer (11) is coated with a reflective layer (29), preferably made of a metal, by vapor deposition, galvanic or chemical deposition.

Claim 21 has been amended, as follows:

21. (Amended) A method according to ~~one of claims 17~~
~~through 20 claim 17,~~ characterized in that the interspaces (12)
in the structured thin glass layer (11, 17) are filled with a
filling material (14, 18) having a refractive index lower than
the refractive index of the glass of the thin glass layer (11,
17).

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